

L Number	Hits	Search Text	DB	Time stamp
3	3039	(mems or micromachine\$2) with (polysilicon or silicon)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:17
4	2504	((mems or micromachine\$2) with (polysilicon or silicon)) and (al or aluminum)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:18
5	1713	((((mems or micromachine\$2) with (polysilicon or silicon)) and (al or aluminum)) and temperature\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:18
6	462	(((((mems or micromachine\$2) with (polysilicon or silicon)) and (al or aluminum)) and temperature\$2) and (titanium or ti))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:19
7	415	((((((mems or micromachine\$2) with (polysilicon or silicon)) and (al or aluminum)) and temperature\$2) and (titanium or ti)) and etch\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:20
8	276	((((((((mems or micromachine\$2) with (polysilicon or silicon)) and (al or aluminum)) and temperature\$2) and (titanium or ti)) and etch\$4) and free	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:19
9	103	((((((((mems or micromachine\$2) with (polysilicon or silicon)) and (al or aluminum)) and temperature\$2) and (titanium or ti)) and (etch\$4 same free)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:23
11	36	((((((((mems or micromachine\$2) with (polysilicon or silicon)) and (al or aluminum)) and temperature\$2) and (titanium or ti)) and (etch\$4 same free)) and ((silicon or polysilicon) same sputter\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:24
10	27	((((((((mems or micromachine\$2) with (polysilicon or silicon)) and (al or aluminum)) and temperature\$2) and (titanium or ti)) and (etch\$4 same free)) and ((silicon or polysilicon) with sputter\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/04/19 11:24